



A Study in Meeting the Allowable 2% Reject Rate in the Production of SOT453A  
Units at NXP Semiconductors Cabuyao Inc. From June to November 2013  
Amounting to Php 18,810,360.00

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## ABSTRACT

This study entitled “A Study in Meeting the Allowable 2% Reject Rate in the Production of SOT453A Units at NXP Semiconductors Cabuyao Inc. From June to November 2013 Amounting to Php 18,810,360.00” has the objective of meeting the allowable 2% reject rate in the production of SOT453A Units at NXP Semiconductors Cabuyao Inc. The researcher also wants to enhance the performance of the machines used in the production of SOT453A Units, to assure the compliance to the working instructions implemented by the company and to ensure and standardize that the adjustment setting process is correct. The gathered data were based from the interviews and actual observations done starting from the first process of the production of SOT453A units in the sawing area up to the last process in the back-end area. Upon the analysis of the data, the researcher found out that the machine’s defective parts where the product is interacting is the highest contributor to the rejects. Next to it is the contribution of the stubbornness of the workers in the company. Lastly, having insufficient working instructions of the company also contributes to the reject rate that NXP Semiconductors Cabuyao Inc. is experiencing. In order to eliminate those contributors to the reject rates that the company is experiencing, the researcher proposes to replace the defective machine parts used in the production of SOT453A units, implementation of sanctions to the workers, attachment of part-sensing, inductive and radar sensors and also the implementation of sufficient working instructions in the company.

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